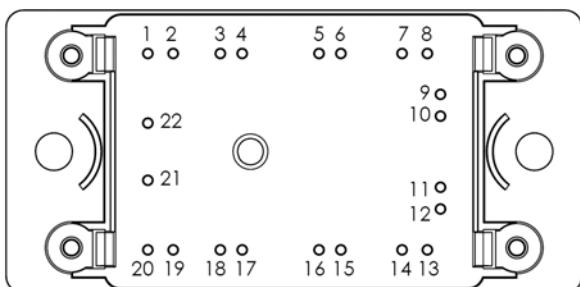
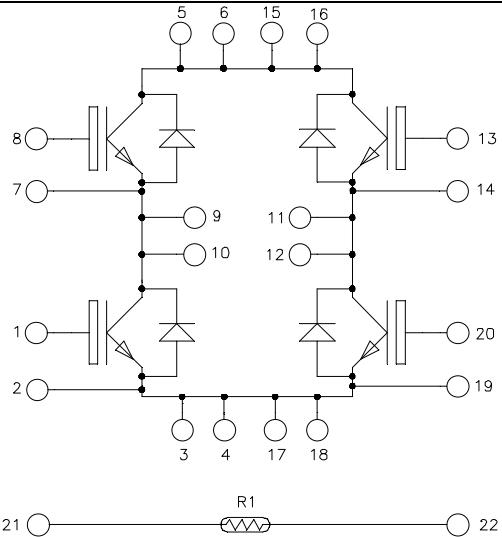


**Full - Bridge  
Trench + Field Stop IGBT3  
Power Module**
**V<sub>CES</sub> = 600V  
I<sub>C</sub> = 75A @ T<sub>c</sub> = 80°C**


Pins 5/6/15/16 ; 3/4/17/18 ; 9/10 ; 11/12 must be shorted together

**Application**

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

**Features**

- Trench + Field Stop IGBT3 Technology
  - Low voltage drop
  - Low tail current
  - Switching frequency up to 20 kHz
  - Soft recovery parallel diodes
  - Low diode VF
  - Low leakage current
  - RBSOA and SCSOA rated
- Very low stray inductance
- Internal thermistor for temperature monitoring
- High level of integration

**Benefits**

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- RoHS Compliant

**All ratings @ T<sub>j</sub> = 25°C unless otherwise specified**
**Absolute maximum ratings (per IGBT)**

Symbol	Parameter	Max ratings	Unit
V <sub>CES</sub>	Collector - Emitter Breakdown Voltage	600	V
I <sub>C</sub>	Continuous Collector Current	T <sub>C</sub> = 25°C	A
		T <sub>C</sub> = 80°C	
I <sub>CM</sub>	Pulsed Collector Current	T <sub>C</sub> = 25°C	140
V <sub>GE</sub>	Gate – Emitter Voltage	±20	V
P <sub>D</sub>	Maximum Power Dissipation	T <sub>C</sub> = 25°C	250
RBSOA	Reverse Bias Safe Operating Area	T <sub>J</sub> = 150°C	150A @ 550V

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

**Electrical Characteristics** (per IGBT)

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I <sub>CES</sub>	Zero Gate Voltage Collector Current	V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V				250	μA
V <sub>CE(sat)</sub>	Collector Emitter Saturation Voltage	V <sub>GE</sub> = 15V	T <sub>j</sub> = 25°C		1.5	1.9	V
		I <sub>C</sub> = 75A	T <sub>j</sub> = 150°C		1.7		
V <sub>GE(th)</sub>	Gate Threshold Voltage	V <sub>GE</sub> = V <sub>CE</sub> , I <sub>C</sub> = 600μA		5.0	5.8	6.5	V
I <sub>GES</sub>	Gate – Emitter Leakage Current	V <sub>GE</sub> = 20V, V <sub>CE</sub> = 0V				600	nA

**Dynamic Characteristics** (per IGBT)

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
C <sub>ies</sub>	Input Capacitance	V <sub>GE</sub> = 0V		4620			pF
C <sub>oes</sub>	Output Capacitance	V <sub>CE</sub> = 25V		300			
C <sub>res</sub>	Reverse Transfer Capacitance	f = 1MHz		140			
Q <sub>G</sub>	Gate charge	V <sub>GE</sub> = ±15V, I <sub>C</sub> = 75A V <sub>CE</sub> = 300V		0.8			μC
T <sub>d(on)</sub>	Turn-on Delay Time	Inductive Switching (25°C) V <sub>GE</sub> = ±15V V <sub>Bus</sub> = 300V I <sub>C</sub> = 75A R <sub>G</sub> = 4.7Ω		110			ns
T <sub>r</sub>	Rise Time			45			
T <sub>d(off)</sub>	Turn-off Delay Time			200			
T <sub>f</sub>	Fall Time			40			
T <sub>d(on)</sub>	Turn-on Delay Time	Inductive Switching (150°C) V <sub>GE</sub> = ±15V V <sub>Bus</sub> = 300V I <sub>C</sub> = 75A R <sub>G</sub> = 4.7Ω		120			ns
T <sub>r</sub>	Rise Time			50			
T <sub>d(off)</sub>	Turn-off Delay Time			250			
T <sub>f</sub>	Fall Time			60			
E <sub>on</sub>	Turn-on Switching Energy	V <sub>GE</sub> = ±15V V <sub>Bus</sub> = 300V I <sub>C</sub> = 75A R <sub>G</sub> = 4.7Ω	T <sub>j</sub> = 25°C T <sub>j</sub> = 150°C	0.35 0.6			mJ
E <sub>off</sub>	Turn-off Switching Energy		T <sub>j</sub> = 25°C T <sub>j</sub> = 150°C	2.2 2.6			mJ
I <sub>sc</sub>	Short Circuit data	V <sub>GE</sub> ≤ 15V ; V <sub>Bus</sub> = 360V t <sub>p</sub> ≤ 6μs ; T <sub>j</sub> = 150°C		380			A
R <sub>thJC</sub>	Junction to Case Thermal Resistance					0.60	°C/W

**Reverse diode ratings and characteristics (per diode)**

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V <sub>RRM</sub>	Maximum Peak Repetitive Reverse Voltage			600			V
I <sub>RM</sub>	Maximum Reverse Leakage Current	V <sub>R</sub> =600V				250	µA
I <sub>F</sub>	DC Forward current			T <sub>c</sub> = 80°C	75		A
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> = 75A V <sub>GE</sub> = 0V	T <sub>j</sub> = 25°C T <sub>j</sub> = 150°C		1.6 1.5	2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 75A V <sub>R</sub> = 300V di/dt = 2000A/µs	T <sub>j</sub> = 25°C T <sub>j</sub> = 150°C	100 150			ns
Q <sub>rr</sub>	Reverse Recovery Charge		T <sub>j</sub> = 25°C T <sub>j</sub> = 150°C	3.6 7.6			µC
E <sub>r</sub>	Reverse Recovery Energy		T <sub>j</sub> = 25°C T <sub>j</sub> = 150°C	0.85 1.8			mJ
R <sub>thJC</sub>	Junction to Case Thermal Resistance					0.98	°C/W

**Temperature sensor NTC**

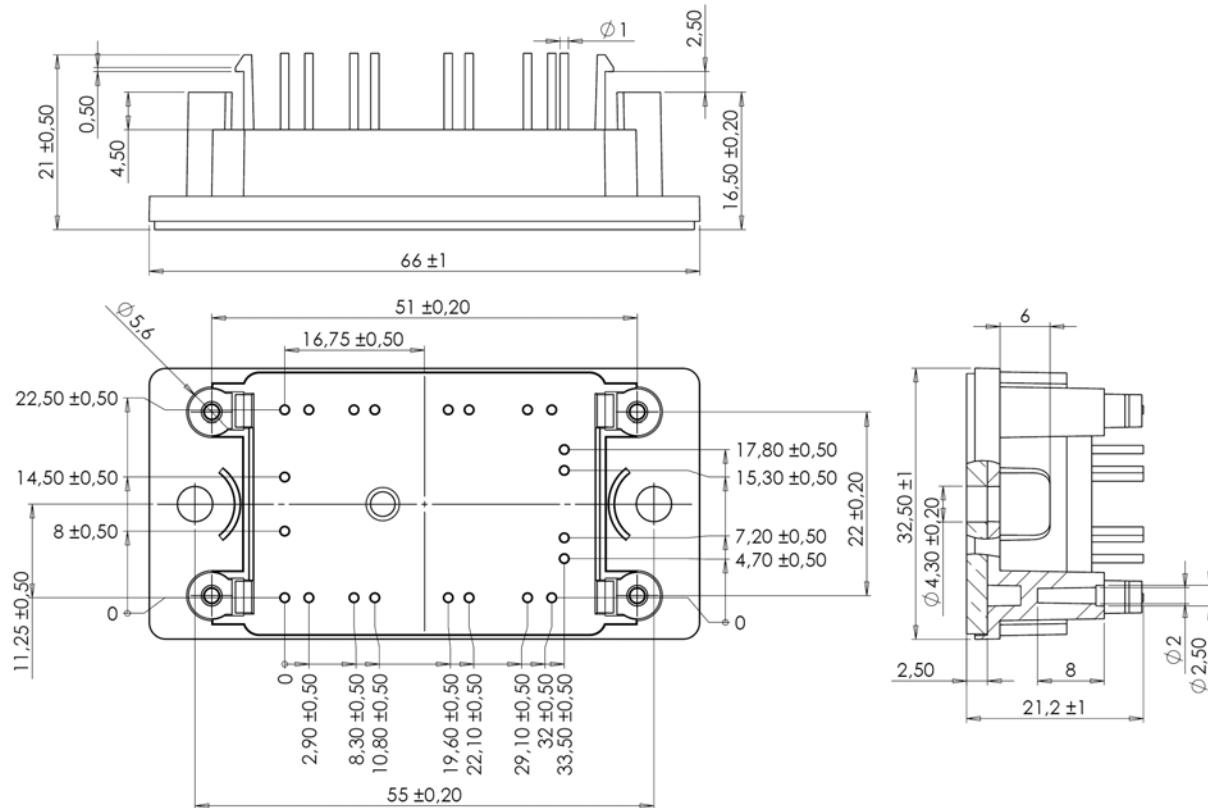
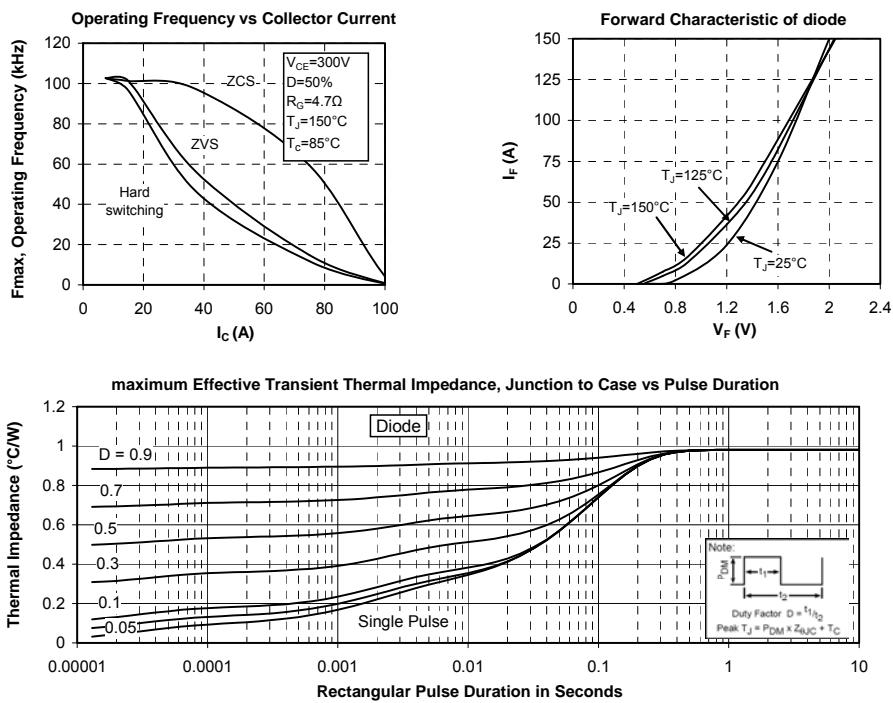
Symbol	Characteristic	Min	Typ	Max	Unit
R <sub>25</sub>	Resistance @ 25°C		22		kΩ
ΔR <sub>25</sub> /R <sub>25</sub>	Resistance tolerance			5	%
ΔB/B	Beta tolerance			3	
B <sub>25/100</sub>	T <sub>25</sub> = 298.16 K		3980		K

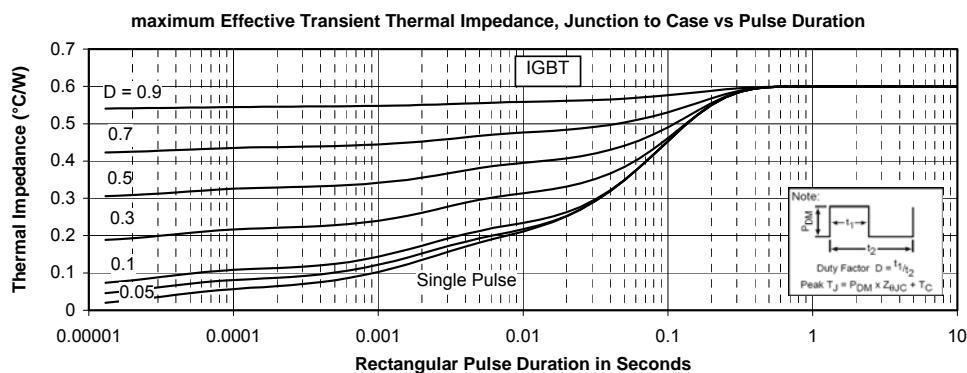
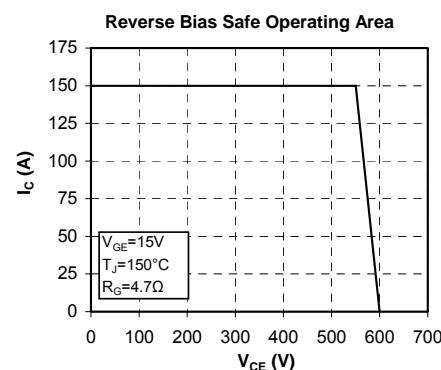
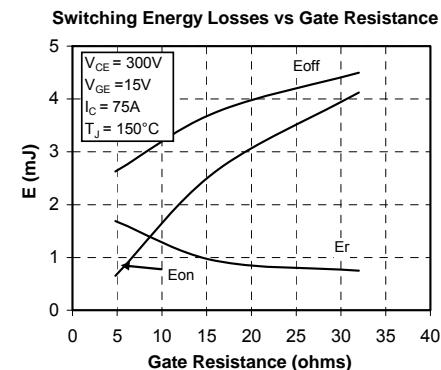
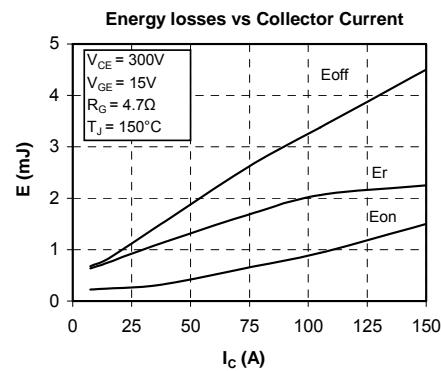
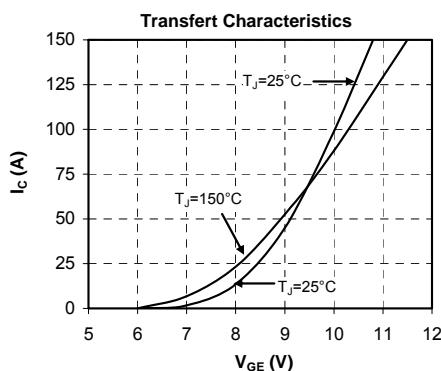
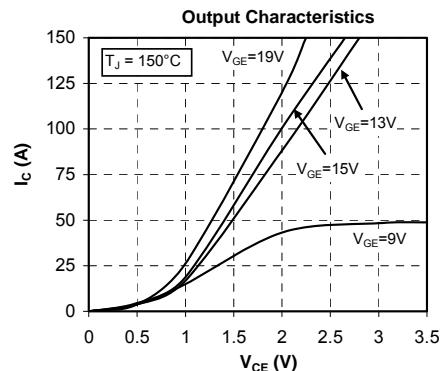
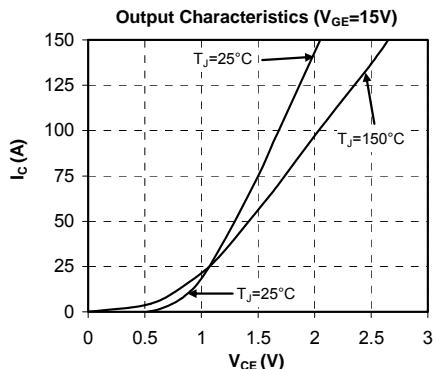
$$R_T = \frac{R_{25}}{\exp\left[B_{25/100}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

T: Thermistor temperature  
R<sub>T</sub>: Thermistor value at T

**Thermal and package characteristics**

Symbol	Characteristic	Min	Typ	Max	Unit	
V <sub>ISOL</sub>	RMS Isolation Voltage, any terminal to case t = 1 min, I isol<1mA, 50/60Hz	4000			V	
T <sub>J</sub>	Operating junction temperature range	-40		175	°C	
T <sub>STG</sub>	Storage Temperature Range	-40		125		
T <sub>C</sub>	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package Weight			75	g	

**Package outline** (dimensions in mm)

**Typical Performance Curve**




Microsemi reserves the right to change, without notice, the specifications and information contained herein